

AN 127:184228 HCA  
 TI **Copper alloy** suitable for electric part showing high  
 adhesion with metal platings  
 IN Suzuki, Takeshi; Sakakibara, Tadao  
 PA Mitsubishi Shindo K. K., Japan  
 SO Jpn. Kokai Tokkyo Koho, 12 pp.  
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 DT Patent  
 LA Japanese  
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	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 09209061	A2	19970812	JP 1996-18898	19960205
AB	The title <b>Cu alloy</b> contains <b>Ni</b> 0.5-3; Si 0.08-0.7; <b>Sn</b> 0.1-0.9; <b>Zn</b> 0.1-3; Fe 0.007-0.25; <b>P</b> 0.001-0.2; Mg 0.001-0.2; Pb 0.001-0.01; Li, In, Ba, Pd, Au, Pt, Rh, and/or Ir 0.0002-0.05 (as total); and optionally Cr 0.01-0.3 and/or				
Zr	0.01-0.3 wt.%. The alloy shows same tensile strength, elongation, elec. cond., as those of ordinary <b>Cu alloys</b> for elec. part.				

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